

ABSTRACT OF THE DISCLOSURE

Disclosed is a component mounting apparatus including two board transfer devices for respectively transferring circuit boards in respective directions parallel to each other and a component placing device provided with at least one component placing head for mounting the components on the boards positioned at predetermined mounting positions on the board transfer devices. Where two component placing heads are provided, they pick up components from two component supply devices and mount the picked-up components respectively on the boards loaded by the two board transfer devices. In this way, the component placing device mounts components simultaneously or alternately on two boards loaded respectively by the two board transfer devices. While one of the two board transfer devices is transferring a board thereon or while the one board transfer device is being adjusted to alter its transfer way width, one of the component placing heads for performing component mountings at the one board transfer device helps the other component placing head in performing component mountings at the other board transfer device. In a modified form, either one of the two transfer devices is used as bypass conveyor or return conveyor.